



EPO-TEK® MED-314

Technical Data Sheet
For Reference Only

Biocompatible/High Temperature, Low Index Epoxy

ISO 10993-5 Tested/Compliant

Date: May 2025
Rev: I
No. of Components: Two
Mix Ratio by Weight: 100 : 6
Specific Gravity: Part A: 1.18 Part B: 1.23
Pot Life: 4 Days
Shelf Life- Bulk: One year at room temperature
Shelf Life- Syringe: Six months at -40°C

Biocompatible Certified Cure: 150°C / 1 Hour

Alternative biocompatible cure schedules may be possible, but have not been certified. Contact med@epotek.com with any questions.

NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.
- Syringe packaging will impact initial viscosity and effective pot life, potentially beyond stated parameters.

Product Description: EPO-TEK® MED-314 is a biocompatible, high temperature grade, thermally and electrically insulating epoxy, designed for adhesive and sealing applications found in the medical industry. It is a low viscosity optical grade epoxy with low index of refraction (Nd).

Typical Properties: Cure condition: 150°C / 1 Hour Different batches, conditions & applications yield differing results.

Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

PHYSICAL PROPERTIES:

* Color (before cure):	Part A: Clear/Colorless	Part B: Amber
* Consistency:	Pourable liquid	
* Viscosity (23°C) @ 100 rpm:	300-600	cPs
Thixotropic Index:	N/A	
* Glass Transition Temp:	≥ 75	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)
Coefficient of Thermal Expansion (CTE):		
Below Tg:	39	x 10 ⁻⁶ in/in°C
Above Tg:	134	x 10 ⁻⁶ in/in°C
Shore D Hardness:	83	
Lap Shear @ 23°C:	N/A	psi
Die Shear @ 23°C:	≥ 15	Kg 5,334 psi
Degradation Temp:	361	°C
Weight Loss:		
@ 200°C:	0.18	%
@ 250°C:	0.43	%
@ 300°C:	1.03	%
Suggested Operating Temperature:	< 300	°C (Intermittent)
Storage Modulus:	275,210	psi
Particle Size:	N/A	

OPTICAL PROPERTIES:

Spectral Transmission:	≥ 96% @ 440-1680	nm
Refractive Index:	1.4965 @589	nm

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This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product.

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